

### **REMARKS**

This Amendment is in response to the Office Action mailed on April 20, 2006. Claims 1 and 3-5 have been currently amended. Claims 1, 3 and 4 have been amended to further clarify elements recited in the claims and are supported, for example, by Figures 5-12 and in the specification on page 10, lines 17-24, page 11, lines 4-14 and page 12, line 22-page 13, line 1. Claim 5 is amended to track with claim 4. As a result, no new material has been added. Claim 2 has been cancelled without prejudice. Claims 1 and 3-5 remain pending.

#### **Rejections to Claims 1-3:**

Claims 1-3 were rejected as being obvious over Maeda. This rejection is traversed. Maeda does not teach or suggest all the limitations of claims 1 and 3. Claims 1 and 3 are directed to a capacitor element with beveled or rounded surfaces connected to an end surface that is opposite the end surface from which an anode wire projects. In contrast, Maeda teaches a capacitor element in which beveled surfaces ("1c") are formed on a first surface ("1") from which an anode wire ("2") projects. Nowhere does Maeda teach or suggest a capacitor element in which beveled or rounded surfaces are formed on the surface opposite that from which an anode projects.

Furthermore, Maeda provides no motivation to modify its capacitor element to meet the limitations of claims 1 and 3. Namely, Maeda provides no motivation to connect beveled or rounded surfaces to the end surface of the chip body that is opposite the end surface from which an anode wire projects. Claims 1 and 3 require beveled or rounded surfaces connected to two opposite sides of an end surface that is opposite the end surface from which an anode wire projects, while the other pair of sides has a line junction. As the chip body is immersed into an electrolyte solution with the anode wire oriented upward, surface tension causes the electrolyte solution to gather at the sides of the end surface that have a line junction. When the electrolyte solution solidifies, it forms larger bumps along the sides of the end surface that have a line junction than on the sides of the end surface connected to the beveled or rounded surfaces. This prevents bumps from occurring equally along all four sides, which would hinder the soldering of a cathode lead terminal on all four sides surfaces. In contrast, Maeda discusses beveled surfaces ("1c") formed on all four sides of first surface ("1") to prevent or restrain an

electrolyte solution from flowing over the top face ("1a") of the capacitor chip ("1"), thereby reducing the likelihood that the formed solid electrolyte layer will extend beyond the dielectric coating and into direct contact with the anode wire ("2") (see col. 4, lines 56-63). For at least these reasons, claims 1 and 3 are not unpatentable and should be allowed.

Rejections to Claims 4-5:

Claims 4 and 5 were rejected as being obvious over Mitsui in view of Maeda. This rejection is traversed. Maeda is cited in this rejection for the same teachings as in the previous rejection. As discussed above, Maeda is not relevant to the present invention. Accordingly, claim 4 is not obvious and should be allowed. Claim 5 depends from claim 4 and therefore should also be allowed for at least the same reasons.

Conclusion:


Applicant respectfully asserts claims 1 and 3-5 are now in condition for allowance. If a telephone conference would be helpful in resolving any issues concerning this communication, please contact Applicants' primary attorney-of record, Douglas P. Mueller (Reg. No. 30,300), at (612) 455-3804.



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Respectfully submitted,

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